

Dr. Craig Hillman, CEO and Managing Partner

Expertise in best practices in Design for Reliability (DfR), strategies for transitioning to Pb-free, supplier qualification (commodity and engineered products), passive component technology (capacitors, resistors, etc.), and printed board failure mechanisms. Over 40 publications and has presented on a wide variety of reliability issues to over 200 companies / organizations.

Post-Doctoral Fellowship (Cambridge University)

PhD, Materials (University of California Santa Barbara)

B.S., Metallurgical Eng. & Material Science (Carnegie Mellon)

Dr. Nathan Blattau, Vice President

Has been involved in the packaging and reliability of electronic equipment for over eight years. Is highly experienced in failure analysis and accelerated testing methods. His primary research interests are in the areas of design-for-reliability in electronic packaging, nonlinear finite element analysis, solder joint reliability, fracture, and fatigue mechanics of materials.

PhD, Mechanical Engineering (University of Maryland)

M.S., Mechanical Engineering (University of Maryland)

B.S., Civil Engineering (University of Maryland)

Dr. Gerd Fischer, Senior Member of Technical Staff

Has more than 15 years experience in solid state physics, materials and device development, and analytical procedures, with an emphasis on failure analysis and design. He is a member of the German Physical Society and the American Physical Society. Has authored or co-authored 25 articles. He is fluent in English, German and Danish.

PhD, Physics (University of Tübingen, Germany)

Diploma in Physics (University of Tübingen, Germany)